

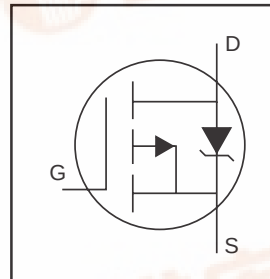
International IOR Rectifier

PD - 94577

IRFI9610G

HEXFET® Power MOSFET

- Isolated Package
- High Voltage Isolation=2.5KVRMS ⑤
- Sink to Lead Creepage Dist.=4.8mm
- P-Channel
- Dynamic dv/dt Rating
- Low thermal Resistance



$$V_{DSS} = -200V$$

$$R_{DS(on)} = 3.0\Omega$$

$$I_D = -2.0A$$

Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness. Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220 Fullpak eliminates the need for additional insulating hardware in commercial-industrial applications. The moulding compound used provides a high isolation capability and a low thermal resistance between the tab and external heatsink. This isolation is equivalent to using a 100 micron mica barrier with standard TO-220 product. The Fullpak is mounted to a heatsink using a single clip or by a single screw fixing.



TO-220 Full-Pak

Absolute Maximum Ratings

	Parameter	Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-2.0	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ -10V$	-1.3	
I_{DM}	Pulsed Drain Current ①	-8.0	
$P_D @ T_C = 25^\circ C$	Power Dissipation	27	W
	Linear Derating Factor	0.22	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E_{AS}	Single Pulse Avalanche Energy②	100	mJ
I_{AR}	Avalanche Current①	-2.0	A
E_{AR}	Repetitive Avalanche Energy①	2.7	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-11	V/ns
T_J	Operating Junction and	-55 to + 150	°C
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	

Thermal Resistance

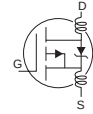
	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	---	4.6	°C/W
$R_{\theta JA}$	Junction-to-Ambient	---	65	

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Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	-200	—	—	V	V _{GS} = 0V, I _D = -250μA
ΔV _{(BR)DSS} /ΔT _J	Breakdown Voltage Temp. Coefficient	—	-0.22	—	V/°C	Reference to 25°C, I _D = -1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance	—	—	3.0	Ω	V _{GS} = -10V, I _D = -1.2A ④
V _{GS(th)}	Gate Threshold Voltage	-2.0	—	-4.0	V	V _{DS} = V _{GS} , I _D = -250μA
g _{fs}	Forward Transconductance	0.7	—	—	S	V _{DS} = -50V, I _D = -1.2A
I _{DSS}	Drain-to-Source Leakage Current	—	—	-100	μA	V _{DS} = -200V, V _{GS} = 0V
		—	—	-500		V _{DS} = -160V, V _{GS} = 0V, T _J = 125°C
I _{GSS}	Gate-to-Source Forward Leakage	—	—	100	nA	V _{GS} = 20V
	Gate-to-Source Reverse Leakage	—	—	-100		V _{GS} = -20V
Q _g	Total Gate Charge	—	—	13	nC	I _D = -2.0A
Q _{gs}	Gate-to-Source Charge	—	—	3.2		V _{DS} = -160V
Q _{gd}	Gate-to-Drain ("Miller") Charge	—	—	7.3		V _{GS} = -10V, See Fig. 6 and 13 ④
t _{d(on)}	Turn-On Delay Time	—	12	—	ns	V _{DD} = -100V I _D = -2.0A R _G = 24Ω V _{GS} = -10V, See Fig. 10 ④
t _r	Rise Time	—	17	—		
t _{d(off)}	Turn-Off Delay Time	—	19	—		
t _f	Fall Time	—	15	—		
L _D	Internal Drain Inductance	—	4.5	—	nH	Between lead, 6mm (0.25in.) from package and center of die contact
L _S	Internal Source Inductance	—	7.5	—		
C _{iss}	Input Capacitance	—	180	—	pF	V _{GS} = 0V
C _{oss}	Output Capacitance	—	66	—		V _{DS} = -25V
C _{rss}	Reverse Transfer Capacitance	—	12	—		f = 1.0MHz, See Fig. 5



Source-Drain Ratings and Characteristics

	Parameter	Min.	Typ.	Max.	Units	Conditions
I _S	Continuous Source Current (Body Diode)	—	—	-2.0	A	MOSFET symbol showing the integral reverse p-n junction diode.
I _{SM}	Pulsed Source Current (Body Diode) ①	—	—	-8.0		
V _{SD}	Diode Forward Voltage	—	—	-5.8	V	T _J = 25°C, I _S = -2.0A, V _{GS} = 0V ④
t _{rr}	Reverse Recovery Time	—	130	200	ns	T _J = 25°C, I _F = -2.0A
Q _{rr}	Reverse Recovery Charge	—	700	1050	nC	di/dt = -100A/μs ④
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by L _S +L _D)				

Notes:

① Repetitive rating; pulse width limited by max. junction temperature. (See fig. 11)

② Starting T_J = 25°C, L = 51mH
R_G = 25Ω, I_{AS} = -2.0A. (See Figure 12)

③ I_{SD} ≤ -2.0A, di/dt ≤ -250A/μs, V_{DD} ≤ V_{(BR)DSS},
T_J ≤ 150°C

④ Pulse width ≤ 300μs; duty cycle ≤ 2%.

⑤ t = 60s, f = 60Hz.

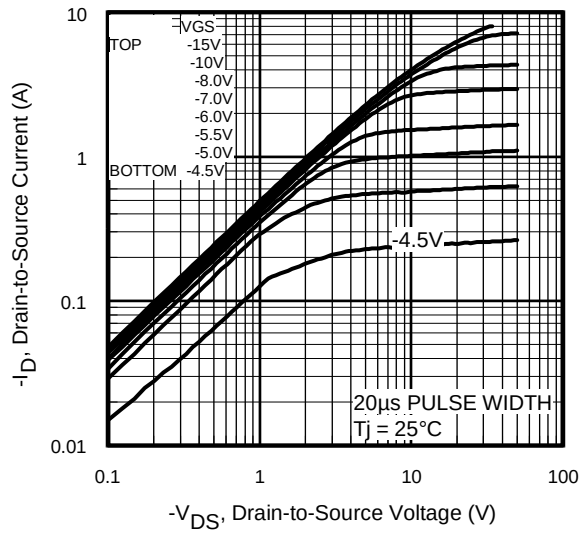


Fig 1. Typical Output Characteristics,
 $T_J = 25^\circ\text{C}$

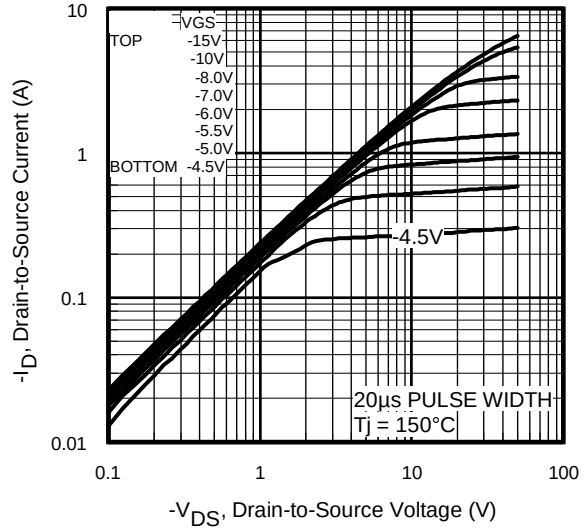


Fig 2. Typical Output Characteristics,
 $T_J = 150^\circ\text{C}$

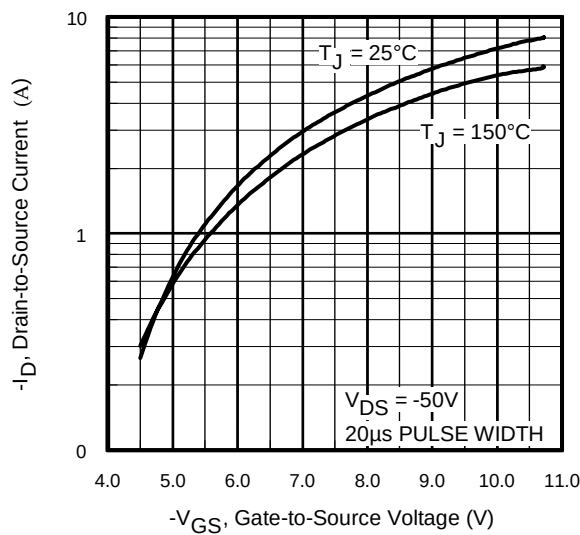


Fig 3. Typical Transfer Characteristics

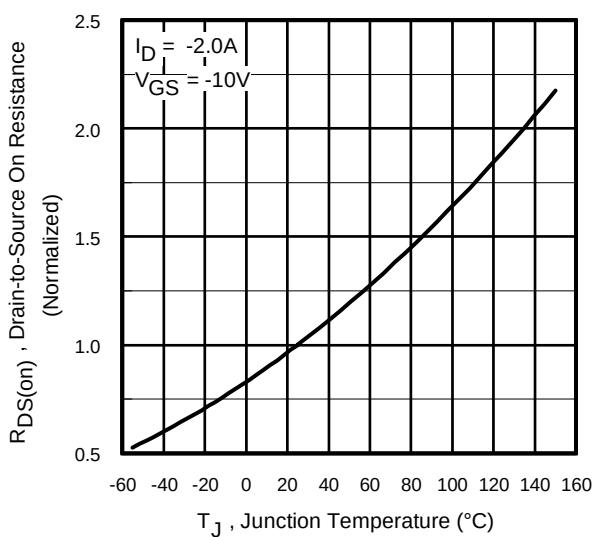


Fig 4. Normalized On-Resistance
Vs. Temperature

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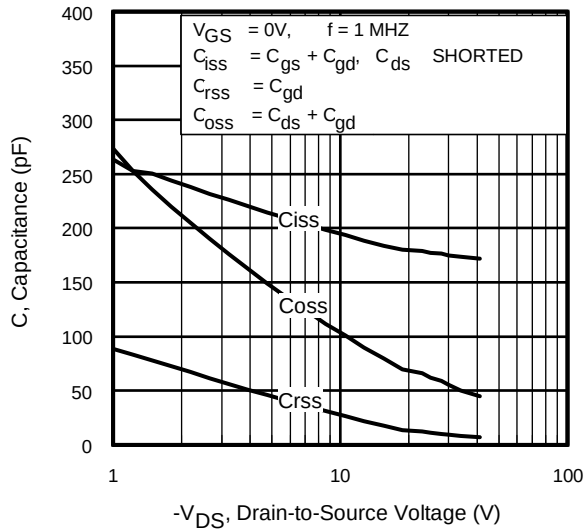


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

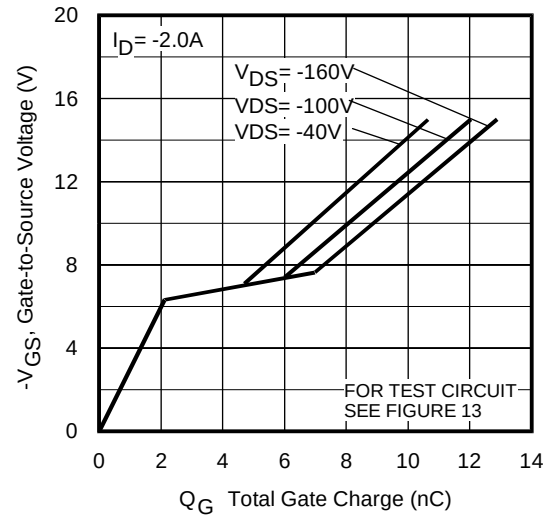


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

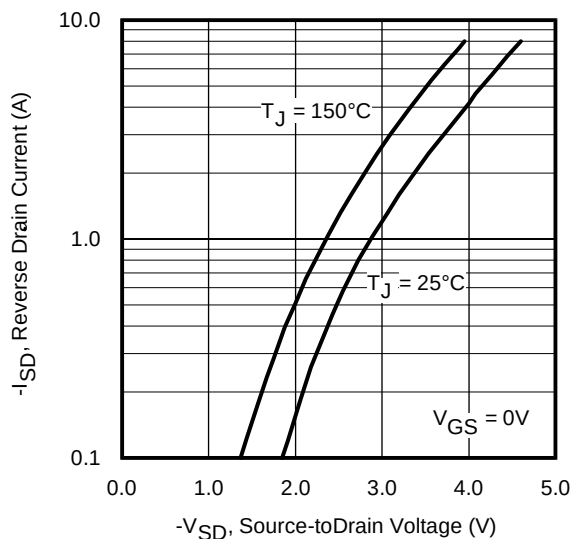


Fig 7. Typical Source-Drain Diode Forward Voltage

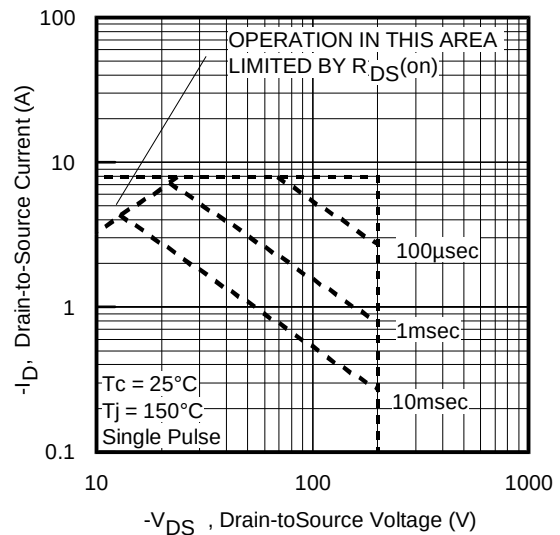


Fig 8. Maximum Safe Operating Area

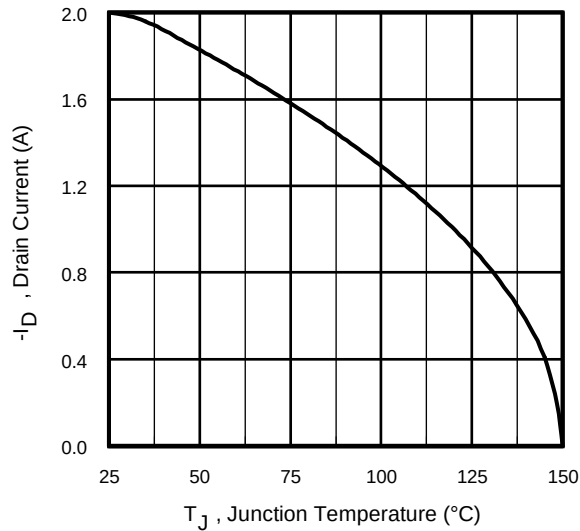


Fig 9. Maximum Drain Current Vs. Case Temperature

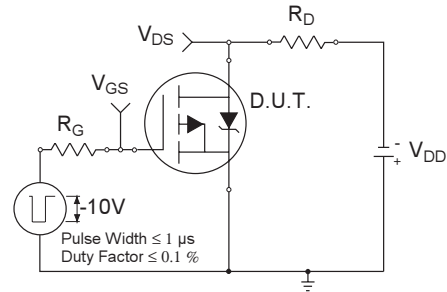


Fig 10a. Switching Time Test Circuit

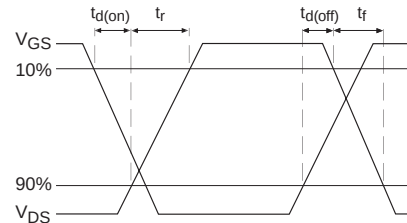


Fig 10b. Switching Time Waveforms

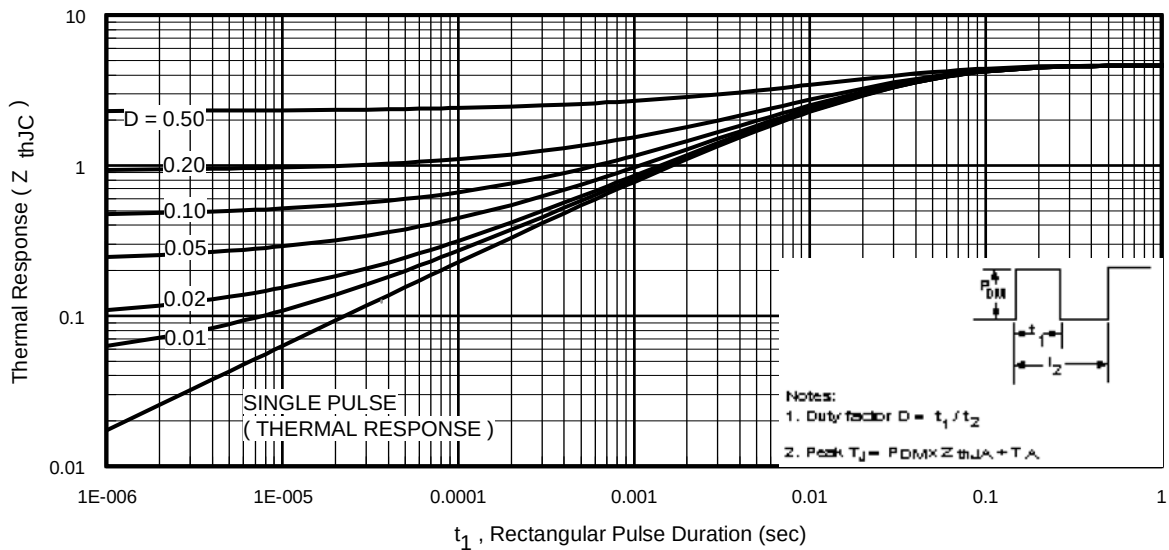


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

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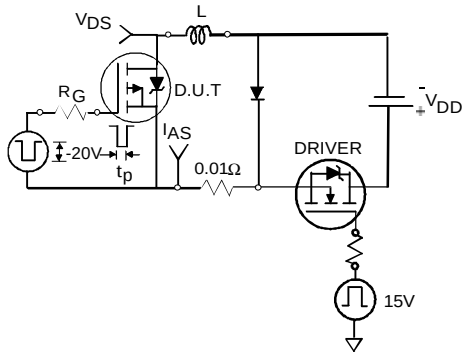


Fig 12a. Unclamped Inductive Test Circuit

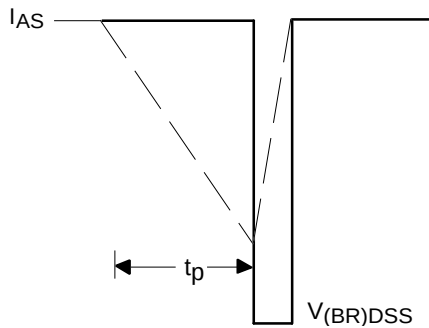


Fig 12b. Unclamped Inductive Waveforms

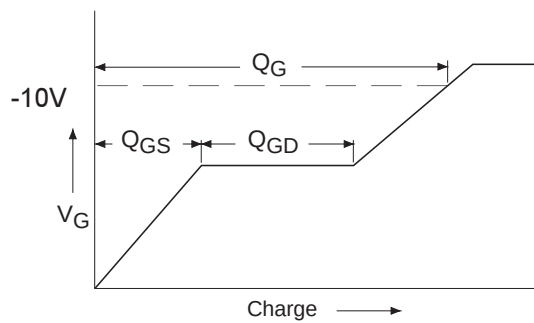


Fig 13a. Basic Gate Charge Waveform

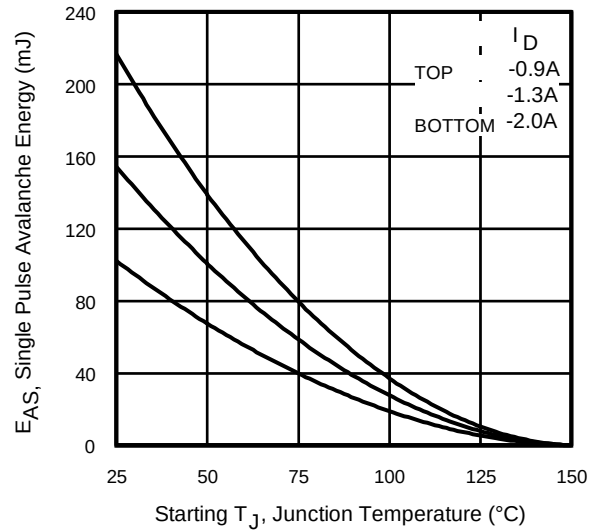


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

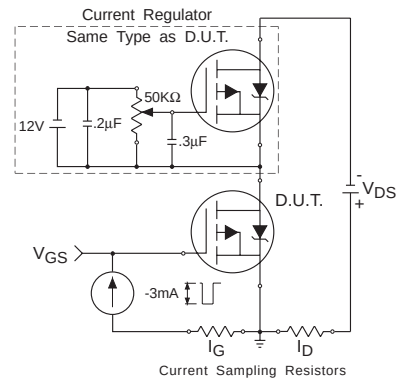
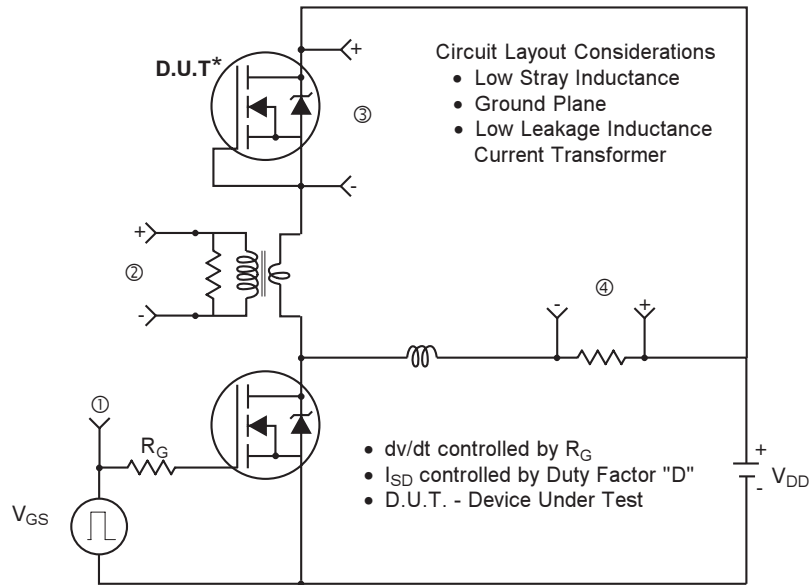
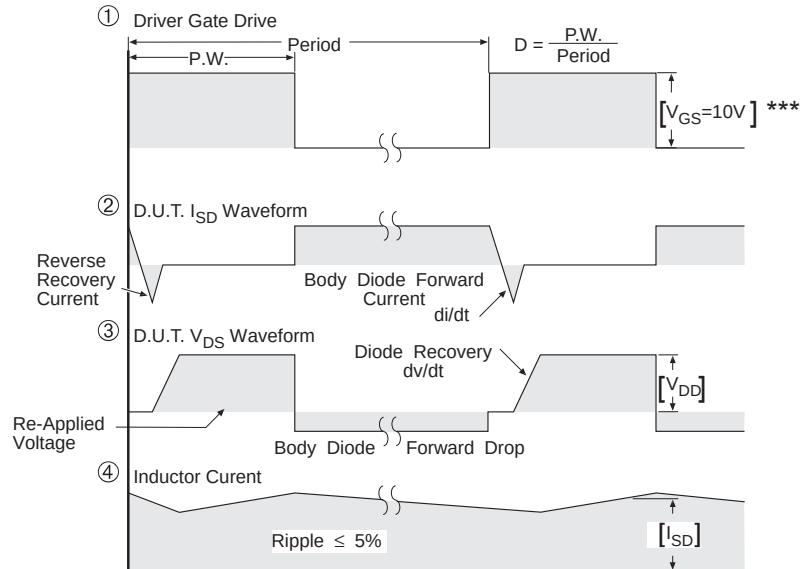


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



* Reverse Polarity of D.U.T for P-Channel



*** $V_{GS} = 5.0V$ for Logic Level and 3V Drive Devices

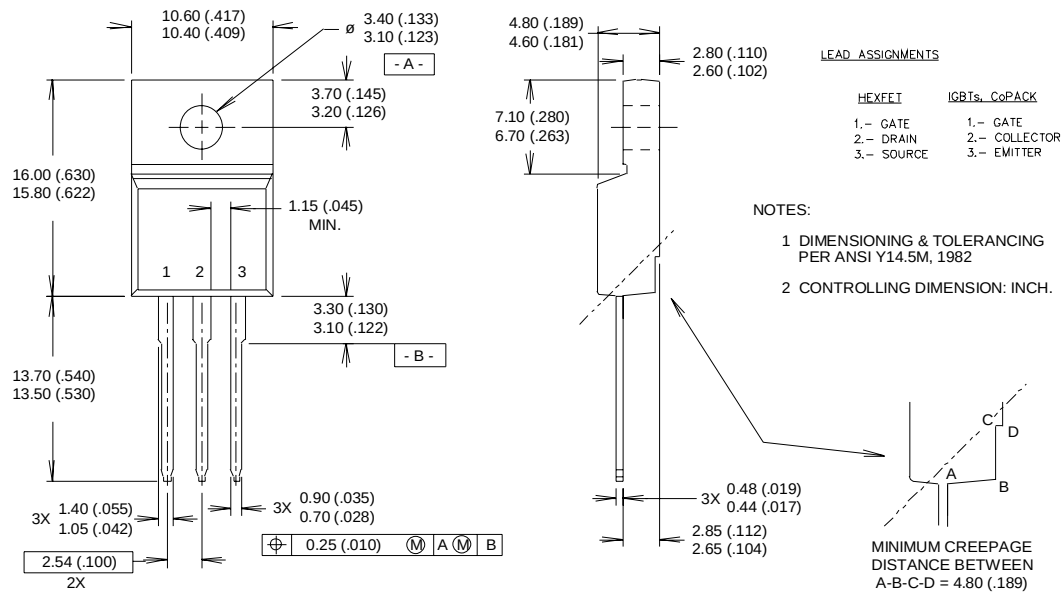
Fig 14. For P-Channel HEXFETS

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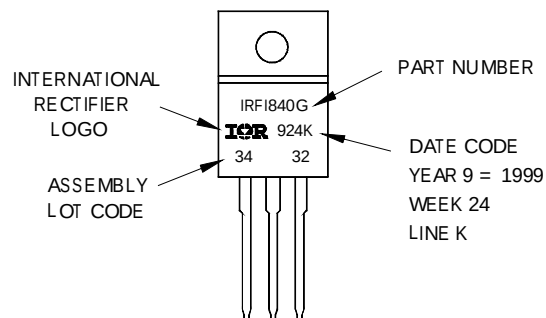
TO-220 Full-Pak Package Outline

Dimensions are shown in millimeters (inches)



TO-220 Full-Pak Part Marking Information

EXAMPLE: THIS IS AN IRFI840G
WITH ASSEMBLY
LOT CODE 3432
ASSEMBLED ON WW 24 1999
IN THE ASSEMBLY LINE "K"



Data and specifications subject to change without notice.
Qualification Standards can be found on IR's Web site.

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